

PAL10/10016P8 ECL Programmable Array Logic

General Description

The PAL1016P8/10016P8 is the first member of an ECL programmable logic device family possessing common electrical characteristics, utilizing an easily accommodated programming procedure, and produced with National Semiconductor's advanced oxide-isolated process. This family includes combinatorial, and registered output devices.

These devices are fabricated using National's proven Ti-W (Titanium-Tungsten) fuse technology to allow fast, efficient, and reliable programming.

This family allows the designer to quickly implement the defined logic function by removing the fuses required to properly configure the internal gates and/or registers. Product terms with all fuses removed assume a logical high state. All devices in this series are provided with an output polarity fuse that, if removed, will permit any output to independently provide a logic low when the equation is satisfied. When these fuses are intact the outputs provide a logic true (most positive voltage level) in response to the input conditions defined by the applicable equation. All input and I/O pins have on-chip 50 k Ω pull-down resistors.

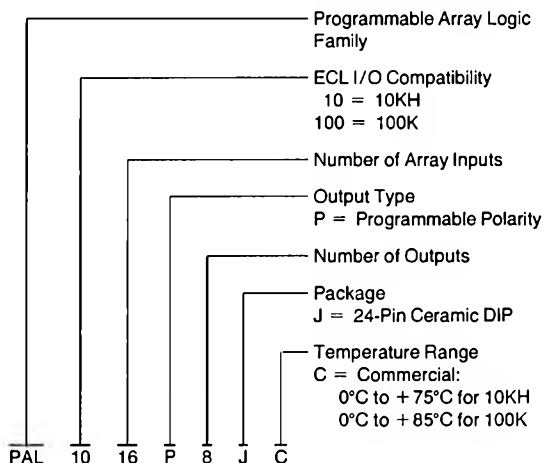
Fuse symbols have been omitted from the logic diagrams to allow the designer use of the diagrams to create fuse maps representing the programmed device.

All devices in this family can be programmed using conventional programmers. After the device has been programmed and verified, an additional fuse may be removed to inhibit further verification or programming. This "security" feature can provide a proprietary circuit which cannot easily be duplicated.

Features

- $t_{PD} = 6$ ns max
- Eight combinatorial outputs with programmable polarity
- Programmable replacement for conventional ECL logic
- Both 10KH and 100K I/O compatible versions
- Simplifies prototyping and board layout
- 24-pin thin DIP packages.
- Programmed on conventional TTL PLD programmers
- Security fuse to prevent direct copying
- Reliable titanium-tungsten fuses

Ordering Information



Absolute Maximum Ratings

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Temperature Under Bias (Ambient)	–55°C to +125°C
Storage Temperature Range	–65°C to +150°C
V_{EE} Relative to V_{CC}	–7V to +0.5V
Any Input Relative to V_{CC}	V_{EE} to +0.5V

Lead Temperature (Soldering, 10 seconds)	300°C
ESD Tolerance	1000V
C_{ZAP}	= 100 pF
R_{ZAP}	= 1500 Ω
Test Method:	Human Body Model
Test Specification:	NSC SOP-5-028

Recommended Operating Conditions

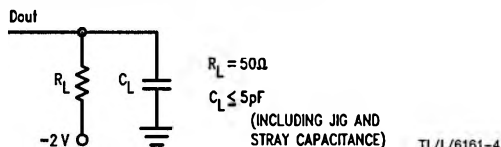
Symbol	Parameter		Min	Typ	Max	Units
V_{EE}	Supply Voltage	10 kH	–5.46	–5.2	–4.94	V
		100k	–4.73	–4.5	–4.27	
R_L	Standard 10 kH/100k Load			50		Ω
C_L	Standard 10 kH/100k Load			5		pF
T_A	Operating Ambient Temperature	10 kH	0		+75	°C
		100k	0		+85	

Electrical Characteristics

Over Recommended Operating Conditions. Output Load = 50 Ω to –2.0V.

Symbol	Parameter	Conditions	T_A	Min	Max	Units
V_{IH}	High Level Input Voltage	Guaranteed input voltage high for all inputs	10 kH	0°C +25°C +75°C	–1170 –1130 –1070	mV
			100k	0°C to 85°C	–1165 –880	
V_{IL}	Low Level Input Voltage	Guaranteed input voltage low for all inputs	10 kH	0°C +25°C +75°C	–1480 –1480 –1450	mV
			100k	0°C to 85°C	–1810 –1475	
V_{OH}	High Level Output Voltage	$V_{IN} = V_{IH}$ Max. or V_{IL} Min.	10 kH	0°C +25°C +75°C	–1020 –980 –920	mV
			100k	0°C to 85°C	–1025 –880	
V_{OL}	Low Level Output Voltage	$V_{IN} = V_{IH}$ Max. or V_{IL} Min.	10 kH	0°C +25°C +75°C	–1950 –1950 –1950	mV
			100k	0°C to 85°C	–1810 –1620	
I_{IH}	High Level Input Current	$V_{IN} = V_{IH}$ Max.	10 kH	0°C +75°C	220	μ A
			100k	0°C to 85°C		
I_{IL}	Low Level Input Current	$V_{IN} = V_{IL}$ Min. Except I/O Pins	10 kH	0°C +75°C	0.5	μ A
			100k	0°C to 85°C		
I_{EE}	Supply Current	$V_{EE} =$ Max. All inputs and outputs open	10 kH	0°C to 75°C	–240	mA
			100k	0°C to 85°C		

Note: This product family has been designed to meet the specification in the test table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained.



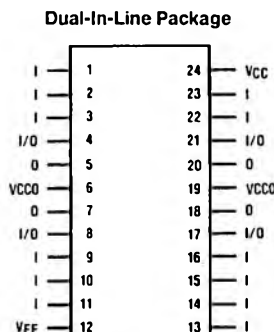
Switching Characteristics

Over Recommended Operating Conditions; Output load: $R_L = 50\Omega$ to $-2.0V$, $C_L = 5\text{ pF}$ to GND.

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
t_{PD}	Input to Output*			4	6	ns
t_r	Output Rise Time		0.5	1	2.5	ns
t_f	Output Fall Time		0.5	1	2.5	ns

*Measure t_{PD} at threshold points

Connection Diagram



TL/L/6161-2

Top View

PAL Design

The first step in designing a PAL device is the selection of the appropriate device to accommodate the logic equations. This is accomplished by partitioning the system into logic blocks with a defined number of inputs and outputs. Next, a device with an equal or greater I/O capability is selected to implement each logic block. The assignment of inputs and outputs to specific pins follows the device selection.

This device selection procedure is most easily accomplished with the use of computer software such as the PLAN™ package of programs by National Semiconductor Corporation, but can be done manually using the logic diagram and logic symbols provided in this document.

Specifying the Fuse Pattern

Once a device with pinout is selected, the fuse pattern may be specified. The best procedure is the use of the PLAN, or a similar software package which will create the fuse pattern from the defined logic for the device and download the pattern to a programmer. Most common device programmers are provided with an RS-232 port which accesses the data provided in JEDEC or a selected HEX format.

Logic diagrams can be translated to PAL logic diagrams if desired. Fuses left intact are indicated on the logic diagram by an "X" at the intersection of the input line and the AND gate product line. A blown fuse is not marked. The PAL logic diagrams are provided with no fuse locations marked, allowing the designer to use the diagram to manually create a fuse map. Actually, the unprogrammed device is shipped with all Xs (fuses) intact. Each fuse node is identified by a product line number and an input line number.

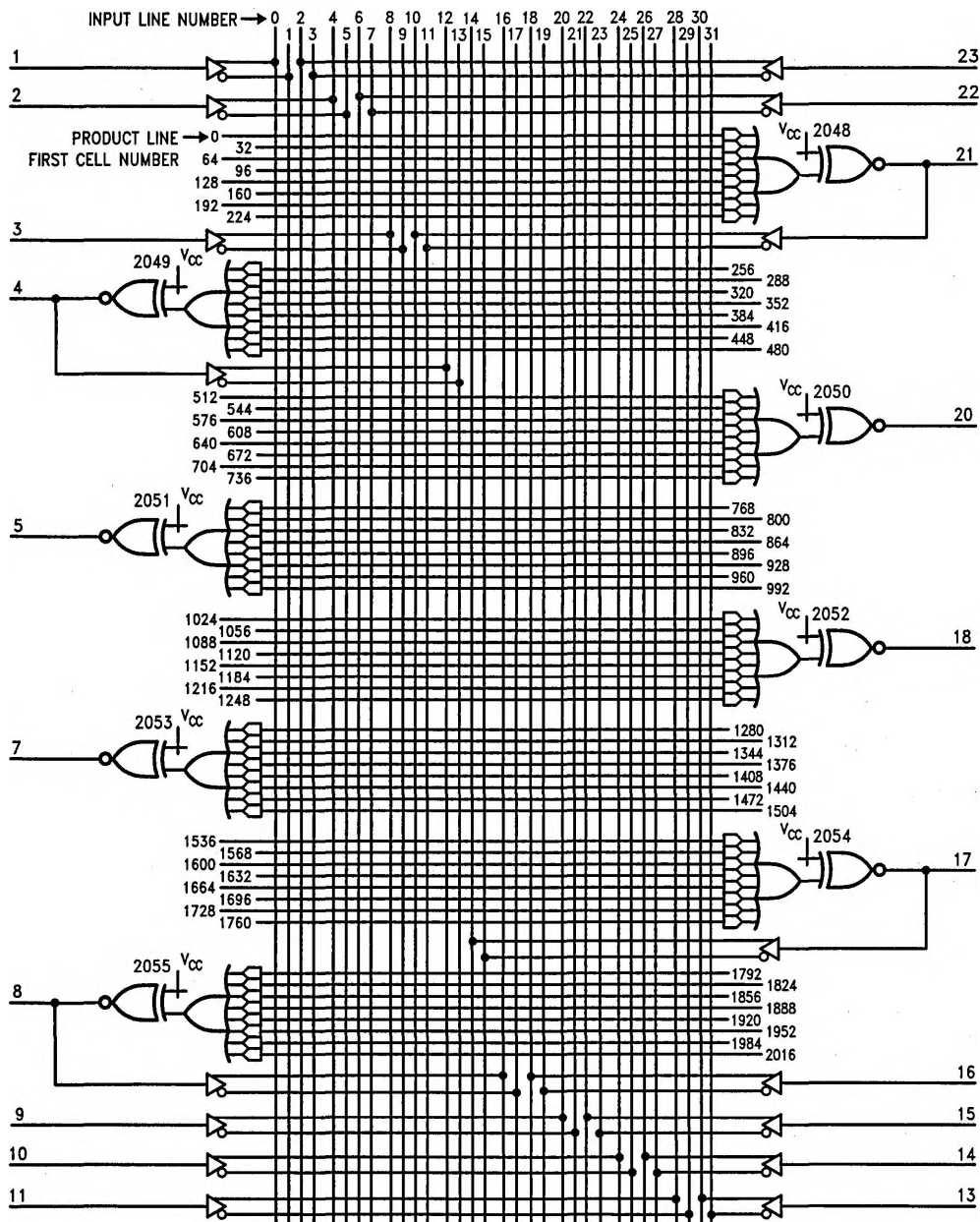
Each device in the ECL PAL family has the capability for its output polarity to be user-determined. The selection of output polarity is logically determined by the equations and implemented, if an active low output is required, by removing the fuse representing the appropriate output.

National Masked Logic

If a large number of devices with the same pattern are required, it may be more economical to consider mask programming. These mask-programmed devices will meet or exceed all of the performance specifications of the fuse-programmed devices they replace.

To generate a mask-programmed device, National Semiconductor requires a set of logic equations, written in a format such as PLAN, plus test vectors which the user generates as acceptance criteria for the finished product.

Logic Diagram PAL1016P8/PAL10016P8



JEDEC logic array cell number = product line first cell number + input line number.

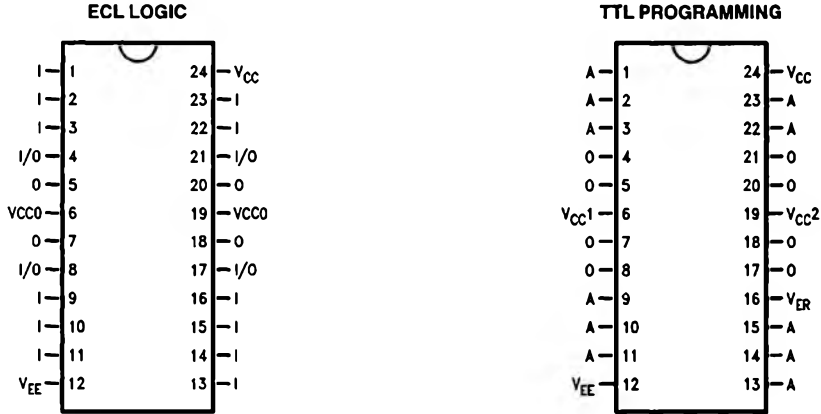
TL/L/6161-3

Programming Specification

This specification defines the programming and verification procedure for the first programmable logic devices in National's generic ECL family. The internal fuse arrays consists of 64 product lines (8 for each output), each containing 32 fuse locations (1 for each of 16 inputs and its complement) for a total of 2048 array fuses. Eight additional fuses exist to allow changing the active output polarity.

Each ECL device is programmed and verified as a 2048x1 TTL PROM. The connection diagrams in *Figure 1* illustrate the difference between the logical ECL device and the PROGRAMMABLE TTL device.

For a list of current software and programming support tools available for these devices, please contact your local National Semiconductor sales representative or distributor.



TL/L/6161-5
FIGURE 1. Connection Diagrams

TL/L/6161-6

Array Fuse Addressing

When programming or verifying a fuse location, the output (equation) is addressed by the 3 address pins 13, 14, and 15. The eight product lines, within the equation, are selected by the 3 address pins 9, 10, and 11. The fuse pair locations representing the logical inputs are selected by the 4 address pins 2, 3, 22, and 23, with the complementing fuse within the pair by the address pin 1. The programming address data is detailed in Tables I–III.

Table I. Logic Output (Equation) Selection vs. Programming Address Inputs.

Output Pin	Address Pin		
	15	14	13
21	0	0	0
4	0	0	1
20	0	1	0
5	0	1	1
18	1	0	0
7	1	0	1
17	1	1	0
8	1	1	1

Note that the sequence of outputs represent the physical, not numeric, order of logical outputs.

Table II. Product Line (within Equation, or Output) vs. Programming Address Inputs.

Product Pin	Address Pin		
	11	10	9
0	0	0	0
1	0	0	1
2	0	1	0
3	0	1	1
4	1	0	0
5	1	0	1
6	1	1	0
7	1	1	1

Table III. Input Line Selection vs. Programming Address Inputs.

Input Line	Address Pin				
	23	22	3	2	1
0	0	0	0	0	0
1	0	0	0	0	1
2	0	0	0	1	0
3	0	0	0	1	1
4	0	0	1	0	0
5	0	0	1	0	1
6	0	0	1	1	0
7	0	0	1	1	1
8	0	1	0	0	0
9	0	1	0	0	1
10	0	1	0	1	0
11	0	1	0	1	1
12	0	1	1	0	0
13	0	1	1	0	1
14	0	1	1	1	0
15	0	1	1	1	1
16	1	0	0	0	0
17	1	0	0	0	1
18	1	0	0	1	0
19	1	0	0	1	1
20	1	0	1	0	0
21	1	0	1	0	1
22	1	0	1	1	0
23	1	0	1	1	1
24	1	1	0	0	0
25	1	1	0	0	1
26	1	1	0	1	0
27	1	1	0	1	1
28	1	1	1	0	0
29	1	1	1	0	1
30	1	1	1	1	0
31	1	1	1	1	1

Note pin 1 affects complementing fuse only.

The array and output polarity fuse programming waveform diagram is shown in *Figure 2*. The 8 output pins 0_N are used only to change the polarity of the selected device output and for removing the “security” fuse. Tables 4 and 5 define the voltage and timing requirements.

Programming Procedure

1. Power is applied to the device. VCC, VCC1, and VCC2 (pins 24, 6, and 19) go to VCC. (The voltage applied to pin 24 cannot precede the voltage applied to pin 6) The output pins (4, 5, 7, 8, 17, 18, 20, and 21), are open circuited, or held at a logic low level, while programming the array.
2. After T₀, VCC1 (pin 6) can be raised from 5.0 to 10.75V at a slow rate not to exceed 10V/ μ S, or not less than 1V/ μ s.
3. The 11 address inputs (pins 1–3, 9–11, 13–15, 22, and 23) will define the location of the array fuse to be opened or the applicable output pin will define the polarity fuse to be opened.

2. After T0, VCC1 (pin 6) can be raised from 5.0 to 10.75V at a slow rate not to exceed 10V/ μ S, or not less than 1V/ μ s.

3. The 11 address inputs (pins 1–3, 9–11, 13–15, 22, and 23) will define the location of the array fuse to be opened or the applicable output pin will define the polarity fuse to be opened.

4. After VCC1 has been stable at 10.75V for period T1 and the address has been stable defining the applicable fuse location for period T2, VCC2 (pin 19) may slew from 5.0 to 10.75V at a slew rate of 1 to 10V/ μ S.

- 5. VCC2 must remain stable at 10.75V for the duration of the programming pulse (TP) before returning to 5.0V.**

6. With VCC1 at 10.75V and after VCC2 has been stable at 5.0V for the period T3, VER pin (16) may be sampled. If the fuse was properly opened, a logic low level will be observed. If the fuse did not open, steps 4 through 6 may be repeated up to 15 times.

7. If additional locations are to be addressed, steps 3 through 6 must be repeated for each fuse to be opened while observing the maximum power up time and duty cycle.

Fuse Verification

Fuse verification may be performed independent of programming. As seen in *Figure 2*, with VCC1 at VCCP and VCC2 at VCC verification may occur within the defined timing constraints. (See Table V)

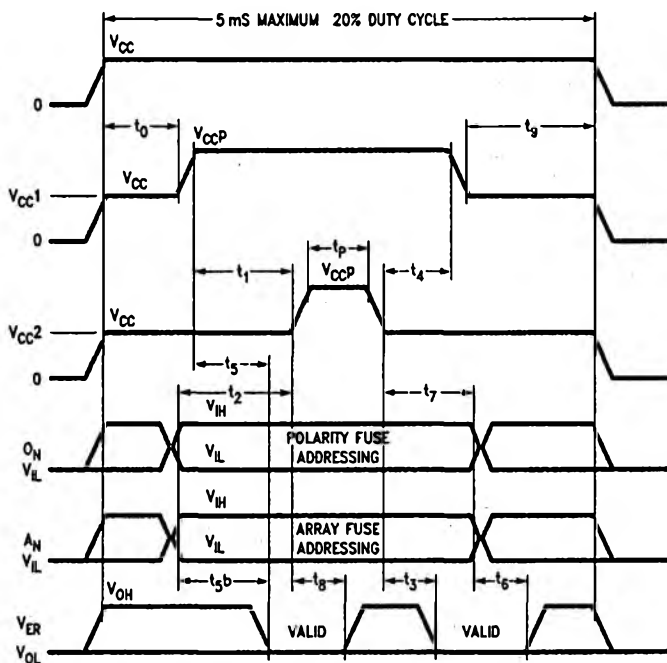


FIGURE 2. Array/Polarity Programming Diagram

TL/L/6161-7

TABLE IV. DC Requirements

Symbol	Description	Min	Nom	Max	Units
V_{CC}	Pin 24 Voltage While Programming or Verifying (Pin 19 Verifying) (Note 1)	4.75	5.00	5.25	V
I_{CC}	Pin 24 Current While Programming (Note 2)		200	300	mA
V_{CCP}	V_{CC1}/V_{CC2} (Pins 6 and 19) Voltage While Programming (Note 3)	10.50	10.75	11.00	V
I_{CC1}	V_{CC1} (Pin 6) Current While Programming (Note 2)		300	450	mA
I_{CC2}	V_{CC2} (Pin 19) Current While Programming (Note 2)		10	25	mA
VIL	Input LOW Level - If Left Open, Pins 4, 5, 7, 8, 17, 18, 20, and 21 are Held Low by Internal 50K Resistor	0		0.8	V
I_{IL}	Input LOW Current - Pins; 1-3, 9-11, 13-15, 22, and 23 $V_{CC}/V_{CC1}/V_{CC2} = \text{Max}, V_{IN} = 0.4V$		-1.0	-1.5	mA
	4, 5, 7, 8, 17, 18, 20, and 21 (Note 4) $V_{CC}/V_{CC1}/V_{CC2} = \text{Max}, V_{IN} = 0.8V$		-0.25	-1.5	mA
V_{IH}	Input HIGH Level	2.20		V_{CC}	V
I_{IH}	Input HIGH Current $V_{CC}/V_{CC1}/V_{CC2} = \text{Max}, V_{IN} = V_{CC} \text{ Max}$ Pins 1-3, 9-11, 13-15, 22, and 23		90	300	μA
	4, 5, 7, 8, 17, 18, 20, and 21		3	5	mA
V_{OL}	Output (Pin 16) LOW Level $V_{CC}/V_{CC1}/V_{CC2} = \text{Min}, I_{OL} = 4 \text{ mA}$			0.8	V
V_{OH}	Output (Pin 16) HIGH Level $V_{CC}/V_{CC1}/V_{CC2} = \text{Max}, I_{OH} = -0.6 \text{ mA}$	2.20			V

Note 1: While programming/verifying, power can be applied to the device for 5 mS maximum with a duty cycle of 20% maximum.

Note 2: Current measurements are taken with $V_{CC}/V_{CC1}/V_{CC2}$ at maximum and with all device inputs and outputs open.

Note 3: The difference between V_{CC} and V_{CCP} must not exceed 6V.

Note 4: If V_{IN} (V_{IL}) is less than 0.8 volts at pins 4, 5, 7, 8, 17, 18, 20, or 21, means must be provided to limit the current sourced by the device pins to 10 mA.

Note 5: All programming and verification to be performed at $25^{\circ}\text{C} \pm 5^{\circ}\text{C}$

TABLE V. Timing

Symbol	Description	Min	Nom	Max	Units
T0	Power-Up Before Raising V_{CC1} (Note 1)	0	500		ns
T1	V_{CC1} at V_{CCP} Before Raising V_{CC2}	400	500		ns
T2	Address Set-Up Time to $V_{CC2} > V_{CCP}$	400	500		ns
T3	VER Valid After V_{CC2} at V_{CC} (Note 2)		200	500	ns
T4	V_{CC2} at V_{CC} Before Lowering V_{CC1}	400	500		ns
T5	VER Valid After Raising V_{CC1} (Note 2)		200	500	ns
T5b	Address Set-Up Time to VER Valid (Note 2)		200	500	ns
T6	VER Valid Hold Time From Address			0	ns
T7	V_{CC2} at V_{CC} Before Address Change	400	500		ns
T8	VER Valid Hold Time From $V_{CC2} > V_{CCP}$ (Note 2)	0	100		ns
T9	V_{CC1} at V_{CC} Before Power Down	0			ns
TP	Programming Pulse	10	10	30	μs

Note 1: Observe the maximum power-up time or 5 ms and duty cycle of 20% for $V_{CC}/V_{CC1}/V_{CC2}$ during programming.

Note 2: VER is valid when $V_{CC2} = V_{CC}$ and $V_{CC1} = V_{CCP}$.

Security Fuse Programming

The security fuse is opened using the same procedure as used for changing the output polarity, except all 8 outputs (pins 4, 5, 7, 8, 17, 18, 20, and 21) must be selected with the application of V_{IH} . Verification is determined by the inability to further verify the array.

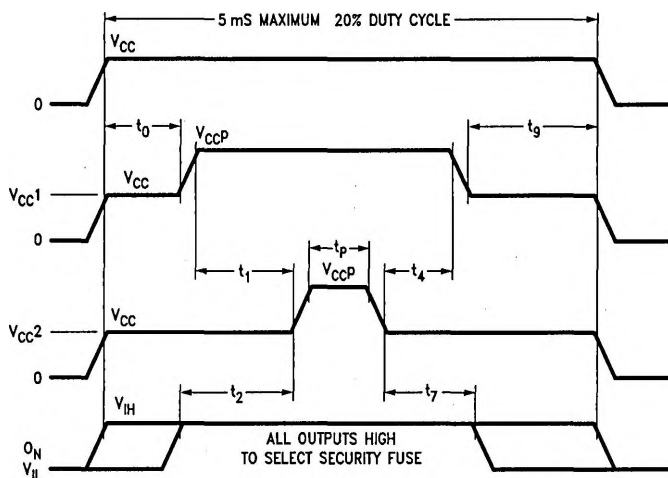


FIGURE 3. Security Fuse Programming Diagram

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